	ne stanu	lard								
	De standard Operating Temperature Range		erature Range	-55 to +105°C (Note1) Stora		age Temperature Range		-10 °C to +60°C (Note3))
Rating	Operating Humidity Range Applicable Connector Voltage		ity Range	20% to 80% (Note2)		Storage Humidity Range		40% to 70%	(Note3))
			nector	DF51%-7S-2C(##)	Curr	ent		AWG 30:0.5A AWG 28 : 1A AWG 22-26 : 2A 30V AC/DC 2.0A		
				250 V AC/DC	UL ∙ Rati	C-UL	Voltage Current			
				Specif	ications	3				
	Item			Test method	oation		Real	uirements	QT	AT
Construc									Q,	///
General Examination		า	Visually and by measuring instrument.			Accordi	According to drawing.			Х
Marking			Confirmed visua	ally.					Х	Х
Electric (eristics								
Contact Resistance		20mV MAX, 1mA (DC or 1000Hz).			30 mΩ	30 mΩ MAX.			-	
Millivolt Level Method		500 1/ 20				1000 MO MIN				
Insulation Resistance		е	500 V DC.							-
Voltage Proof Mechanical Characteris		ractorie	650 V AC for 1 min.			NO TIASI	No flashover or breakdown. X –			
Mechanical Operation (An Plating)		50 times insertion and extraction.			1.No da	1.No damage, crack or looseness of parts. X –				
Mating and unmating Force		It takes out and inserts with a conformity connector.				I.Insertion Force : 33.7N MAX. X – 2.Extraction Force : 1.75N MIN.			-	
(Au Plating)										
Vibration Shock			Frequency 10 to 55 Hz, single amplitude 0.75 mm, at				1.No electrical discontinuity of 1 μ s. X –			_
		10 cycles for 3 direction.			2.No da	2.No damage, crack or looseness of parts.				
		Acceleration 490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.								
Environn		haracte								
Damp Heat (Steady State)			Exposed at 40 \pm 2°C , humidity 90 to 95 %, 96 h. (After leaving the room temperature for 1 to 2h.)					e: 500 M Ω MIN. or looseness of parts.	X	-
Rapid Change Of Temperature		Temperature $-55^{\circ}C \rightarrow +105^{\circ}C$ Time $30min \rightarrow 30min$ Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After the reason temperature for 4 to 2b)				1.Insulation resistance: 1000 MΩ MIN. X 2.No damage, crack or looseness of parts. X			_	
			`	0	- 01- 1					
Drv Heat			After leaving th	e room temperature for 1	o 2h.)				X	<u> </u>
Cold Remarks			(After leaving th Exposed at Exposed at	e room temperature for 1 t 105±2°C, 96h -55±3°C, 96h	to 2h.)	_			X X	_
Note 2:No Note 3:App	condensir	ng condition	(After leaving th Exposed at Exposed at ure rising by curr of long term stor	e room temperature for 1 t 105±2°C, 96h -55±3°C, 96h	efore pcb o	n board, al	fter pcb board	, operating temperature	Х	
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	condensir	ng condition ge is app	(After leaving th Exposed at Exposed at ure rising by curr of long term stor	e room temperature for 1 to 105±2°C, 96h -55±3°C, 96h ent. rage for unused products b torage during transportatio	efore pcb o n.	n board, af	fter pcb board	CHECKED	and DA	
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	condensir oly to the c midity rang	ng condition ge is app	(After leaving th Exposed at Exposed at are rising by curr of long term stor lied for interim s	F REVISIONS	efore pcb o n. DES	SIGNED SUGAWARA		CHECKED SZ. 0N0	X and DA 2023	80711
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	condensir oly to the c midity rang	ng condition ge is app	(After leaving th Exposed at Exposed at are rising by curr of long term stor lied for interim s	F REVISIONS	efore pcb o n. DES	SIGNED SUGAWARA	APPROVED	CHECKED	X and 2023 2022	80711 21024
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	condensir oly to the c midity rang	ng condition ge is app	(After leaving th Exposed at Exposed at are rising by curr of long term stor lied for interim s	F REVISIONS	efore pcb o n. DES	SIGNED SUGAWARA		CHECKED SZ. 0N0	X and 2023 2022 2022	80711 21024 21024
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	OUNT	ng condition ge is app D	(After leaving th Exposed at Exposed at ire rising by curr of long term stor lied for interim s ESCRIPTION O DIS-H-000	F REVISIONS	efore pcb o n. DES	SIGNED SUGAWARA	APPROVED	CHECKED SZ. ONO SJ. OKAMURA	X and 2023 2022 2022	30711 21024
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	OUNT	ng condition ge is app D	(After leaving th Exposed at Exposed at are rising by curr of long term stor lied for interim s	F REVISIONS	efore pcb o n. DES	SIGNED SUGAWARA	APPROVED CHECKED	CHECKED SZ. ONO SJ. OKAMURA TT. OHSAKO	X and 2023 2022 2022 2022	80711 21024 21024
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	Condensir oly to the c midity range OUNT 2 nerwise spo	ng condition ge is app D D	(After leaving th Exposed at Exposed at ire rising by curr of long term stor lied for interim s ESCRIPTION O DIS-H-000	F REVISIONS	efore pcb or n. DES KI. S	SIGNED SUGAWARA	APPROVED CHECKED DESIGNED DRAWN	CHECKED SZ. ONO SJ. OKAMURA TT. OHSAKO KI. SUGAWARA	X and 2023 2022 2022 2022 2022	80711 21024 21024 21021 21021
Cold Remarks Note 1: Inc Note 2:No Note 3:App hui	Condensir oly to the c midity range OUNT 2 erwise sports Qualificati	ng condition ge is app D ecified, re ion Test	(After leaving th Exposed at Exposed at ire rising by curr of long term stor lied for interim s ESCRIPTION O DIS-H-000	F REVISIONS 17930 Fost X:Applicable Test	efore pcb or n. DES KI. S	SIGNED SUGAWARA	APPROVED CHECKED DESIGNED DRAWN	CHECKED SZ. ONO SJ. OKAMURA TT. OHSAKO KI. SUGAWARA KI. SUGAWARA	X and 2023 2022 2022 2022 2022	80711 21024 21024 21021 21021